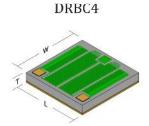
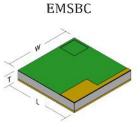
BACK CONTACT CHIP RESISTORS

DRBC3





Mini-Systems, Inc. Back Contact chip resistors offer the high stability, low noise and low TCR of Mini-Systems proven Thin Film technology while providing the design engineer with a space saving alternative in hybrid designs. Each Back Contact Resistor requires only a single wire bond to the top side of the chip with the bottom connection made by eutectic or conductive epoxy attachment to associated circuitry. The EMSBC configurations are single resistors available in several case sizes and a wide resistance range. The DRBC configuration offers two resistors on a single chip and is ideal for use in applications where divider networks with closely matched tolerances and TCR are critical.

GENERAL CHARACTERISTICS

Resistance Range		5Ω to $70 \mathrm{M}\Omega^1$			
Resistor Material		Tantalum Nitride			
Substrate	e Material				
Passi	vation	${ m Ta}_{ m _2}{ m O}_{ m _5}$ (Self Passivating)			
Resistance	e Tolerance				
Terminatio	on Material	Aluminum or Gold			
Termina	ntion Size				
Operating T	Temperature	-55°C to +125°C			
Storage Te	mperature	-65°C to +150°C			
Insulation	Resistance	$10^{12}\Omega$ Min.			
Dielectric l	Breakdown	400V Min.			
Operatin	ig Voltage	100V Max.			
Thermal Condu	ctivity (W/m•K)				
TCR		±150 ppm/°C (Standard) Optional to: ±100 ppm/°C			
TCR Tracking (Dual Resistors Only)		±2ppm/°C			
Current Noise	101Ω to 250kΩ	-35dB			
Current Noise	$\leq 100\Omega > 250 \text{k}\Omega$	-20dB			

¹ Consult Engineering if lower valued resistors are required

PART NUMBER DESIGNATION

EMSBC -	- <u>110</u> -	- S SUBSTRATE	T =	300R0 / 500R0 ² - 10001 OHMIC VALUE	F — TOLERANCE	RN –	E OPTION
EMSBC DRBC	See Tables	S = Silicon	T = Tantalum Nitride	5-Digit Number: 1st 4 digits are significant with "R" as decimal point when required. 5th digit represents number of zeros.	C = 0.25% D = 0.5%	RA = ±0.01% RB = ±0.05% RC = ±0.10% RE = ±0.25% RD = ±0.50% RF = ± 1% RN = No Ratio	F = ±100ppm/°C E = Aluminum Bond Pads G = Gold Bond Pads TR = Tape & Reel

EXAMPLE: EMSBC-110-ST-10001F-E

EMSBC -110 Series, Silicon, Tantalum, 10k Ω ±1% Tol., ±150 ppm/°C, Aluminum Bond Pads

² Use for Dual Resistors Only - (R1 ≤ R2)



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BACK CONTACT CHIP RESISTORS



SINGLE RESISTOR BACK CONTACT SERIES

	STYLE EMSBC	DIMENSIONS		RESISTANCE RANGE				
CASE SIZE		L (±0.003") [±0.076mm]	W (±0.003") [±0.076mm]	T (±0.002") [±0.051mm]	MIN	MAX OPT TCR ±100ppm/°C	MAX STD TCR ±150ppm/°C	POWER RATING ¹
0201	21	0.020" [0.508]	0.010" [0.254]	0.006" [0.152]	5Ω	60kΩ	300kΩ	50mW
0202	1	0.015" [0.381]	0.015" [0.381]	0.010" [0.254]	5Ω	200kΩ	1ΜΩ	50mW
0202	122							125mW
0202	2	0.020" [0.508]	0.020" [0.508]	0.010" [0.254]	5Ω	320kΩ	1.6ΜΩ	250mW
0302	32							250mW
0303	3	0.030" [0.762]	0.030" [0.762]	0.010" [0.254]	5Ω	800kΩ	4ΜΩ	250mW
0402	110							125mW
0404	35	0.035" [0.889]	0.035" [0.889]	0.010" [0.254]	5Ω	1.3ΜΩ	6.5ΜΩ	250mW
0404	4							350mW
0502	115	0.050" [1.270]	0.025" [0.635]	0.010" [0.254]	5Ω	1.3ΜΩ	6.5ΜΩ	250mW
0505	112							500mW
0603	63	0.060" [1.524]	0.030" [0.762]	0.010" [0.254]	5Ω	2.4ΜΩ	11ΜΩ	500mW
0606	6	0.060" [1.524]	0.060" [1.524]	0.010" [0.254]	20Ω	8MΩ	40ΜΩ	500mW
1005	120	0.100" [2.540]	0.050" [1.270]	0.010" [0.254]	5Ω	9ΜΩ	45ΜΩ	500mW
1010	121	0.100" [2.540]	0.100" [2.540]	0.010" [0.254]	10Ω	14ΜΩ	70ΜΩ	750mW
1206	126	0.126" [3.200]	0.063" [1.524]	0.010" [0.254]	10Ω	10ΜΩ	50ΜΩ	750mW

MSBC2 will continue to be available, size and characteristics match EMSBC2. Available with aluminum bond pads only

DUAL RESISTOR BACK CONTACT SERIES

	CTVI E	DIMENSIONS			RESISTANCE RANGE ² Per Resistor			DOWED	
Case	e Size	STYLE DRBC	L (±0.003") [±0.076mm]	W (±0.003") [±0.076mm]	T (±0.002") [±0.051mm]	MIN	MAX OPT TCR ±100ppm/°C	MAX STD TCR ±150ppm/°C	POWER RATING ¹ Per Resistor
03	303	3	0.030" [0.762]	0.030" [0.762]	0.010" [0.254]	5Ω	400kΩ	$2 \mathrm{M}\Omega$	125mW
04	104	4	0.040" [1.060]	0.040" [1.060]	0.010" [0.254]	5Ω	1.2ΜΩ	6ΜΩ	125mW

 $^{^{\}rm 1}$ Power Rating at 70°C Derated Linearly to 0% at 150°C

PERFORMANCE SPECIFICATIONS

PROPERTY	TEST CONDITION	REQUIRED LIMITS	MSI TYPICAL LIMITS	
SHORT TERM OVERLOAD	2.5xWVDC(6.25xRATED POWER)MIL-PRF-55342, +25°C, 5 SEC	±0.25 MAX ΔR/R	±0.10 MAX ΔR/R	
HIGH TEMP EXPOSURE	+150°C, 100HRS	±0.20 MAX ΔR/R	±0.03 MAX ΔR/R	
THERMAL SHOCK	MIL-STD 202, METHOD 107	±0.25 MAX ΔR/R	±0.10 MAX ΔR/R	
MOISTURE RESISTANCE	MIL-STD 202, METHOD 106	±0.40 MAX ΔR/R	±0.10 MAX ΔR/R	
STABILITY	MIL-STD 202 METHOD 108, 2000 HRS, +70°C, RATED POWER	±0.50 MAX ΔR/R	±0.10 MAX ΔR/R	

 $All\,EMSBC, DRBC\,Series\,parts\,are\,produced\,on\,the\,same\,manufacturing\,line\,using\,the\,same\,materials\,and\,processes\,as\,parts\,manufactured\,to\,MIL-PRF-55342$

 $^{^{1}}$ Power Rating at 70°C Derated Linearly to 0% at 150°C

 $^{^{\}rm 2}$ Consult Engineering if lower valued resistors are required

² Consult Engineering if lower valued resistors are required